

Photoluminescence of Ta₂O₅ Films Formed by the Molecular Layer Deposition Method

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Abstract—Ta₂O₅ films of different thicknesses (20–100 nm) synthesized by the molecular layer deposition method on *p*-type silicon substrates and thermally oxidized silicon substrates have been studied by the methods of high-frequency capacitance–voltage characteristics and photoluminescence. A hole-conduction channel is found to form in the Si–Ta₂O₅–field electrode system. A model of the electronic structure of Ta₂O₅ films is proposed based on an analysis of the measured PL spectra and performed electrical investigations.

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One of the high-priority areas of modern solid-state electronics and optoelectronics is improvement of the technology of synthesizing insulators by low-temperature methods [1, 2] (in particular, the molecular layer deposition (MLD) method is most interesting). The MLD technique is based on the sequential use of self-terminating gas–solid chemical reactions. This method is a surface-controlled process, which makes it possible to grow layers of the material with a thickness down to one monolayer. The obtained films are uniform and have an identical thickness over the entire substrate area [3].

There is much interest in development of the process of synthesizing Ta₂O₅, which can be used in static and dynamic random access memory (RAM), new-generation solid-state capacitors characterized by the maximum capacitance-to-size ratio, and external blocking dielectric layers of elements of silicon-based memory and resistive memory [1, 2, 4]. Note that methods of luminescence investigation are intensively used along with electrical methods for diagnostics of semiconductor–insulator structures [5, 6].

The purpose of this study was to optimize the technology of synthesizing Ta₂O₅ layers with different thicknesses by the MLD method and analyze properties of the synthesized (Si–Ta₂O₅) structures by the photoluminescence method.

Ta₂O₅ films (20–100 nm) were grown by the MLD method on silicon substrates (*p*-type, dopant concentration $3 \times 10^{14} \text{ cm}^{-3}$) 100 mm in diameter. We also synthesized layers on Si wafers with a previously formed SiO₂ layer. The silicon wafers were oxidized in oxygen with a minimum water content at 1000°C. The oxide was 50 nm thick. One cycle of the MLD synthe-

sis of a Ta₂O₅ film included two reactions: tantalum chloride (TaCl₅) was used as a precursor in the first reaction, while water vapor was used in the second. Since tantalum chloride is crystalline material at room temperature, the main technological problem of successful implementation of the MLD method is optimization of the technology providing a well-controlled process of TaCl₅ evaporation. Based on the performed investigations, we chose the operating temperature ranges (180–250°C for the silicon substrate temperature and 45–90°C for the evaporator temperature), at which a further synthesis of the Si–Ta₂O₅ and Si–SiO₂–Ta₂O₅ structures was performed. The use of a rotating substrate provided a high film-growth rate.

The electronic structure of the formed Ta₂O₅ layers was identified by the methods of high-frequency capacitance–voltage (*C–V*) characteristics and photoluminescence (PL). *C–V* characteristics were recorded in the metal–insulator–semiconductor and electrolyte–insulator–semiconductor systems. The field electrodes were aluminum and the electrolyte was one-molar solution of sodium sulfate. The PL and PL excitation spectra were recorded by a Fluorolog-3 system (HORIBA Jobin Yvon) consisting of two independent monochromators based on the Czerny–Turner configuration with one diffraction grating of 1200 1/mm. PL excitation was performed by 450-W xenon lamp radiation. The spectra were recorded by the photon-counting method using an R928P photoelectron multiplier. The spectrum scan rate was 150 nm/s. The excitation radiation wavelength was varied in the spectral range of 275–400 nm. The spectral width of the PL excitation monochromator was

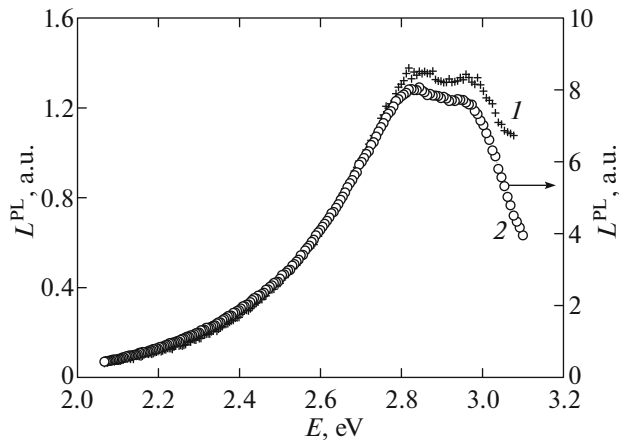


Fig. 1. PL spectra of the (1) Si-Ta₂O₅ (35 nm) and (2) Si-SiO₂ (55 nm)-Ta₂O₅ (100 nm) structures at an excitation energy of 3.35 eV (370 nm).

10 nm, and the spectral width of the luminescence recording monochromator was 5 nm. The PL spectra were recorded in the range determined by the excitation wavelength λ_{exit} (from $(\lambda_{\text{exit}} + 30 \text{ nm})$ to $(2\lambda_{\text{exit}} - 30 \text{ nm})$), which excluded the influence of the second-order diffraction on the recorded PL spectrum. The spectra were corrected for the equipment spectral sensitivity and normalized to the photodiode current proportional to the excitation-lamp intensity.

Photoinjection measurements showed that the Si-Ta₂O₅ structures (with the dielectric-layer thicknesses of 20–100 nm) are characterized by low potential barrier for electrons ($\sim 0.4 \text{ eV}$) at the Si/Ta₂O₅ interface, which is in agreement with the data in the literature [1]. The presence of a low potential barrier for electrons at the semiconductor–insulator interface and significant hole conductivity of the synthesized Ta₂O₅ layers hinder correct measurements of the $C-V$ characteristics of the Si-Ta₂O₅ structures. Therefore, high-frequency $C-V$ characteristics were measured for the Si-SiO₂-Ta₂O₅ structures, in which the SiO₂ layer makes electron and hole exchange between the silicon substrate and Ta₂O₅ layer impossible. As a result, the relative permittivity for Ta₂O₅ films with thicknesses in the range of 20–100 nm was found to be 13.5 ± 0.5 . The Ta₂O₅ film thickness was determined using a Zeiss ORION scanning helium ion microscope from an image of the sample cross section.

Analysis of the PL spectra of the Si-Ta₂O₅ and Si-SiO₂-Ta₂O₅ structures and Si-SiO₂ check structures in the excitation energy range (4.51–3.1 eV) showed that the shape of the PL spectral distribution for the structures with a Ta₂O₅ layer is independent of the type (Si or SiO₂) of substrate used in the synthesis and the Ta₂O₅ layer thickness (in the range of thicknesses under study, 35–150 nm) and that the SiO₂ layer makes no PL contribution at Ta₂O₅ thicknesses

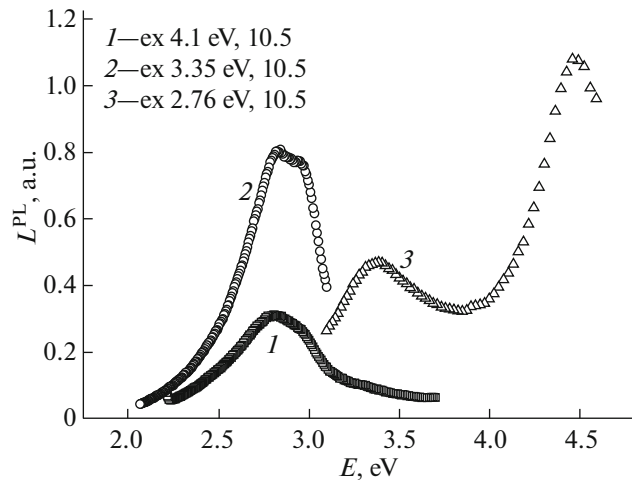


Fig. 2. (1, 2) PL spectra at the excitation energy of (1) 4.1 and (2) 3.35 eV and (3) PL excitation spectra at the energy near 2.78 eV of the Si-SiO₂ (55 nm)-Ta₂O₅ (100 nm) structures.

exceeding 35 nm. Figure 1 shows the PL spectra of the Si-Ta₂O₅ (35 nm) and Si-SiO₂ (55 nm)-Ta₂O₅ (100 nm) structures measured at the excitation energy of 3.35 eV (370 nm). It can be seen that the luminescence intensity is approximately proportional to the tantalum pentoxide layer thickness. Based on the aforesaid, we can conclude that luminescence centers are formed in the volume of tantalum pentoxide directly during its synthesis. In this case, the PL spectra and PL excitation spectra presented in Fig. 2 are completely due to optical processes in the Ta₂O₅ layer.

It was established that all measured PL spectra can be represented in a unified way: as a sum of Gaussian distributions with a fixed energy position, relative intensity, and dispersion. It was found that, for all samples containing tantalum pentoxide, the PL spectrum is a set of emission bands peaking at energies of 2.6 ± 0.1 , 2.8 ± 0.1 , 3.0 ± 0.1 , and $3.2 \pm 0.1 \text{ eV}$. A set of the absorption bands peaking at energies of 3.3 ± 0.1 , 3.9 ± 0.1 , and $4.4 \pm 0.1 \text{ eV}$ was obtained for the PL excitation spectra. The dispersion was $0.20 \pm 0.05 \text{ eV}$ for all bands.

The PL spectra are determined only by radiative processes occurring in the Ta₂O₅ layers and, accordingly, contain information about their electronic structure. The results of expansion of the PL spectra and PL excitation spectra indicate rather complex electronic structure of the tantalum pentoxide layers. The presence of a high-energy band in the PL excitation spectrum with the energy corresponding to the Ta₂O₅ band gap (4.4 eV) [1, 4] allows one to relate the observed PL bands with the set of electronic states energetically located in the Ta₂O₅ band gap. The excitation of luminescence centers with an energy lower than the Ta₂O₅ band gap is related to the optically

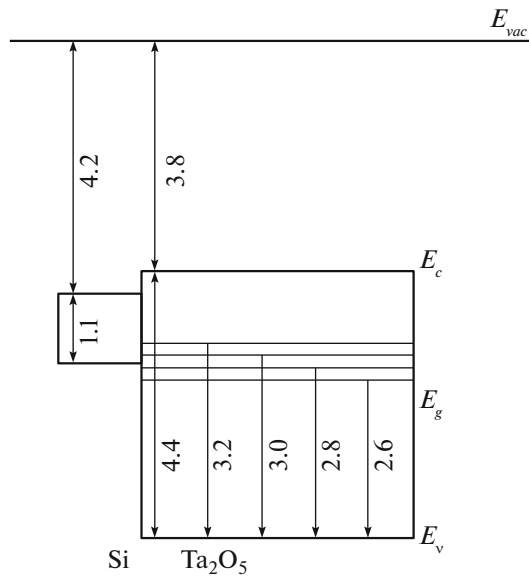


Fig. 3. Energy structure of the Si-Ta₂O₅ structure.

stimulated transition of electrons from the Ta₂O₅ valence band to the corresponding energy level with subsequent radiative relaxation. For example, the PL spectral distribution of Ta₂O₅ upon excitation with an energy near 3.3 eV (Fig. 2, curve 2) consisted of three emission bands peaking at energies of 2.6, 2.8, and 3.0 eV.

Based on the performed analysis, we can propose a model of the electronic structure of tantalum pentoxide layers formed on the silicon (silicon dioxide) surface by the MLD method (Fig. 3).

A schematic shown in Fig. 3 makes it possible to explain the spectral composition of luminescence for any means of its excitation. It is noteworthy that the presence of the system of energy levels located above the top of the Ta₂O₅ valence band by 2.8–3.2 eV in the tantalum pentoxide band gap induces a hole-conduc-

tion channel in the Si-Ta₂O₅-field electrode system; the problems of measuring the high-frequency capacitance of the Si-Ta₂O₅ structures are due to specifically the presence of this channel. The SiO₂ layer in the Si-SiO₂-Ta₂O₅ system prevents the hole current, which makes it possible to measure the high-frequency capacitance in order to study the electrical characteristics of the formed structures.

Thus, Ta₂O₅ layers of different thickness (20–100 nm) were synthesized on a silicon substrate by the low-temperature MLD method. The main electrical characteristics of the formed structures were determined based on high-frequency capacitance and photoluminescence measurements, and a model of their electronic structure was proposed.

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